



Features

- RoHS compliant*
- Low power loss and high efficiency
- High current capability
- Low profile package

Applications

- AC operated products
- Computer monitors
- Set-top boxes
- Cable modems

CD-DF4xxS(L) Series Surface Mount Bridge Rectifier Diode

General Information

The markets of portable communications, computing and video equipment are challenging the semiconductor industry to develop increasingly smaller electronic components.

Bourns offers Bridge Rectifier Diodes for rectification applications in compact chip package 0.41" x 0.32" size format, which offers PCB real estate savings and are considerably smaller than standard parts. The Bridge Rectifier Diodes offer a forward current of 4 A with a choice of repetitive peak reverse voltages between 600 V and 1000 V.



Absolute Maximum Ratings (@ T_A = 25 °C Unless Otherwise Noted)

Parameter	Symbol	CD-						Unit
		DF406S	DF408S	DF410S	DF406SL	DF408SL	DF410SL	
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	600	800	1000	600	800	1000	V
Maximum Average Forward Rectified Current (T _A = 55 °C)	I _{F(AV)}	4.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	150.0						A
Operating Temperature Range	T _J	-55 to +175						°C
Storage Temperature Range	T _{STG}	-55 to +175						°C

Electrical Characteristics (@ T_A = 25 °C Unless Otherwise Noted)

Parameter	Symbol	CD-DF4xxS(L)				Unit	
		Test Conditions		Min.	Typ.		Max.
Instantaneous Forward Voltage	V _F	I _F = 2 A	CD-DF4xxS		0.92	0.95	V
			CD-DF4xxSL		0.86	0.90	
Repetitive Peak Reverse Current	I _{RRM}	V _R = V _{RRM}	T _A = +25 °C		0.08	5.0	μA
Junction Capacitance	C _J	V _R = 4 V, f = 1.0 MHz	CD-DF4xxS		45		pF
			CD-DF4xxSL		45		
Thermal Resistance, Junction to Air (1)	R _{θJA}	CD-DF4xxS			35		°C / W
		CD-DF4xxSL			35		
Thermal Resistance, Junction to Lead (1)	R _{θJL}	CD-DF4xxS			15		°C / W
		CD-DF4xxSL			15		

NOTE 1: Thermal resistance, junction to ambient, measured on PC board with 50 mm² (0.03 mm thick) land areas.

*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.

Specifications are subject to change without notice.

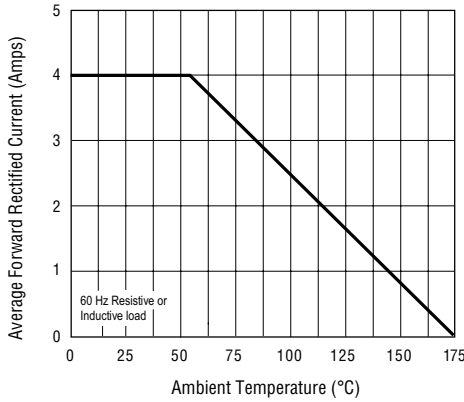
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.

CD-DF4xxS(L) Series Surface Mount Bridge Rectifier Diode

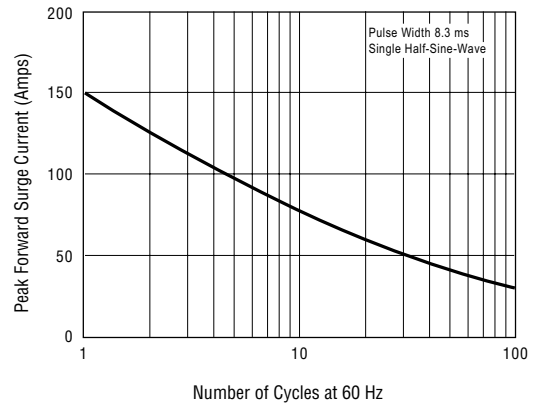
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Rating and Characteristic Curves

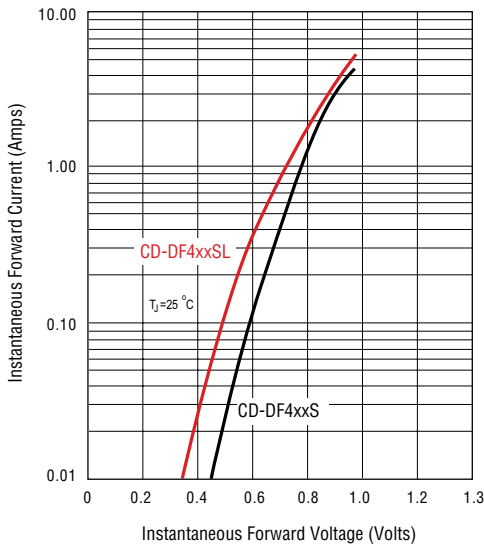
Forward Current Derating Curve



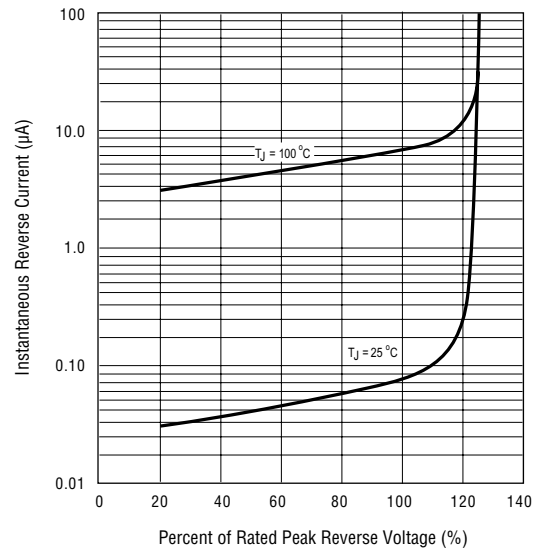
Maximum Non-Repetitive Peak Forward Surge Current



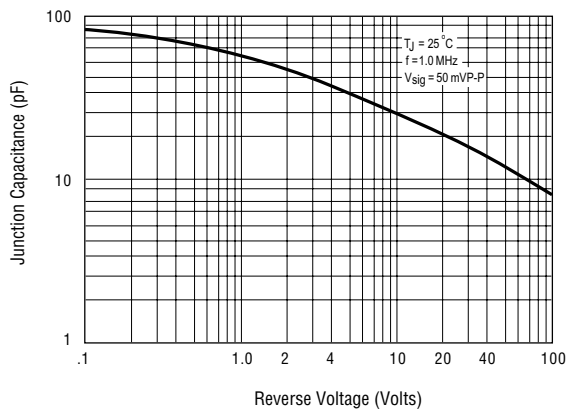
Forward Characteristics



Reverse Characteristics



Typical Junction Capacitance



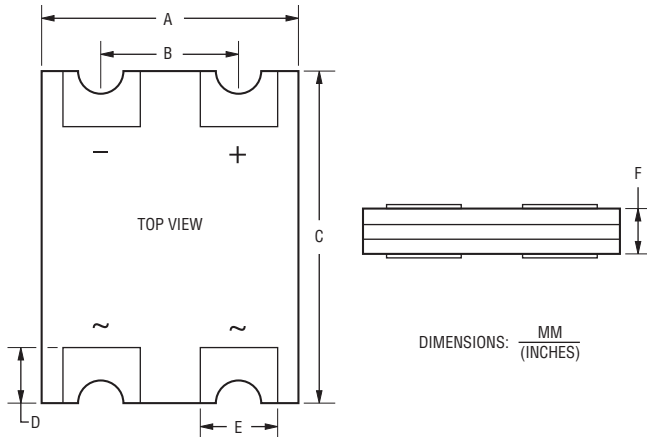
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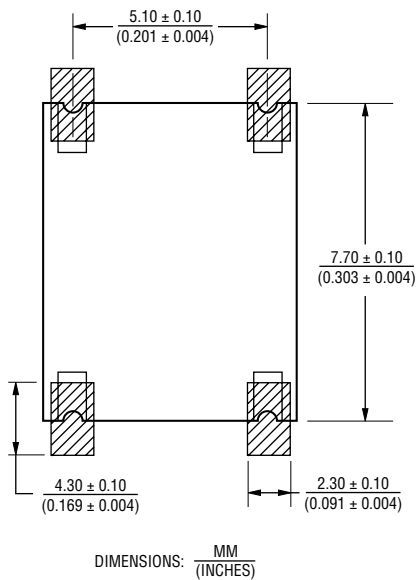
Product Dimensions

This is an RoHS2 compliant product, packaged with FRP substrate and is epoxy underfilled. The terminals are pure tin plated (lead free) and are solderable per MIL-STD-750, Method 2026. The package and dimensions are shown below.

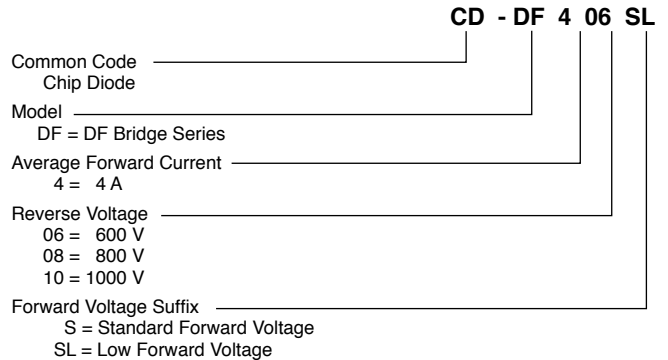


Dimensions	
A	$\frac{8.00 - 8.20}{(0.315 - 0.323)}$
B	$\frac{5.00 - 5.20}{(0.197 - 0.205)}$
C	$\frac{10.40 - 10.60}{(0.409 - 0.417)}$
D	$\frac{1.85 - 2.15}{(0.073 - 0.085)}$
E	$\frac{2.10 - 2.30}{(0.083 - 0.091)}$
F	$\frac{1.25 - 1.55}{(0.049 - 0.061)}$

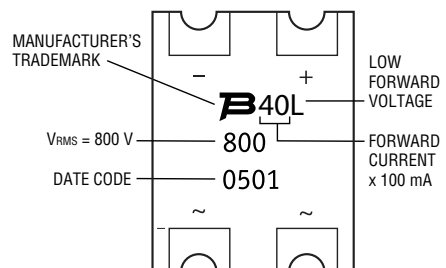
Recommended Footprint



How to Order



Typical Part Marking



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Packaging Information

The surface mount product is packaged in a 16 mm x 12 mm tape and reel format per EIA-481 standard.



Item	Symbol	CD-DF4xxS(L)
Carrier Width	A	$\frac{8.63 \pm 0.38}{(0.34 \pm 0.01)}$
Carrier Length	B	$\frac{11.03 \pm 0.38}{(0.43 \pm 0.01)}$
Carrier Depth	C	$\frac{1.93 \pm 0.38}{(0.08 \pm 0.004)}$
Sprocket Hole	d	$\frac{1.55 \pm 0.05}{(0.061 \pm 0.002)}$
Reel Outside Diameter	D	$\frac{330}{(12.992)}$
Reel Inner Diameter	D ₁	$\frac{50.0}{(1.969)}$ MIN.
Feed Hole Diameter	D ₂	$\frac{13.0 \pm 0.20}{(0.512 \pm 0.008)}$
Sprocket Hole Position	E	$\frac{1.75 \pm 0.10}{(0.069 \pm 0.004)}$
Punch Hole Position	F	$\frac{7.50 \pm 0.10}{(0.295 \pm 0.004)}$
Punch Hole Pitch	P	$\frac{12.00 \pm 0.10}{(0.472 \pm 0.004)}$
Sprocket Hole Pitch	P ₀	$\frac{4.00 \pm 0.10}{(0.157 \pm 0.004)}$
Embossment Center	P ₁	$\frac{2.00 \pm 0.10}{(0.079 \pm 0.004)}$
Overall Tape Thickness	T	$\frac{0.40}{(0.016)}$ MAX.
Tape Width	W	$\frac{16.00 \pm 0.30}{(0.630 \pm 0.012)}$
Reel Width	W ₁	$\frac{22.7}{(0.893)}$ MAX.
Quantity per Reel	--	3,000

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Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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